

Amendments to the Specification:

Page 1, please delete the paragraph added between the title and the heading "BACKGROUND OF THE INVENTION" (that is, between lines 3 and 5), added by the Preliminary Amendment filed June 25, 2003, and substitute therefor the following new paragraph:

--This application is a Divisional application of Application No. 10/182,181, filed July 25, 2002, now U.S. Patent No. 6,821,657, issued November 23, 2004, which is a National Stage Application filed under 35 USC §371 of International (PCT) Application No. PCT/JP0000507, filed January 28, 2000. The contents of Application No. 10/182,181, filed July 25, 2002, are incorporated herein by reference in their entirety.--

Page 34, please delete the paragraph at lines 3-11, and substitute therefor the following new paragraph:

--A paste bonding material 13 containing nickel particles 16 was applied at a thickness of about 50µm between a LSI chip and a wiring board (FR-5) 12 on which there were electrodes 15 made of copper/nickel/gold at a thickness of 20µm, using a syringe 14. Then, while being heated at 200°C and compressed at 30 kg/mm², the LSI chip 17 equipped with gold bumps 18 having a thickness of 20µm was bonded and fixed for 20 seconds onto the wiring board. The product is then heated at 180°C for 60 minutes in an oven to cure the bonding material (cured bonding material 19). For the above, a conductive chip of about 10mm square, equipped with 184 bumps of 80µm in diameter, was used.--

Page 37, please delete the paragraph at lines 3-12, and substitute therefor the following new paragraph:

--Three double-sided printed wiring boards, produced in the same way as described above (the very outer layer is left as bare copper surface), are bonded together using multi-layer bonding prepreg (glass epoxy) 23 having a thickness of 0.1mm, while being heated at 170°C for 90 minutes and compressed under 30 kg/cm², so as to produce a multi-layer board having six wiring layers. A through hole 24 of 0.3mm in diameter is drilled and the paste conductive bonding material 21 is put into the hole in a similar way by printing, and then the board is heated to cure it at 170°C for 60 minutes. Then, after the surface is finished smooth by buffing, the wiring 25 on the very outer layer is formed by etching so as to obtain a six-layer printed wiring board.--